HDMI Companion Chip with I²C Level Shifting Buffer, 12 Channel ESD, and Current-Limit Load Switch

Check for Samples: TPD12S016

FEATURES

- **Conforms to HDMI Compliance Tests without any External Components**
- **Supports HDMI1.4 Data Rate**
- **Match Class D and Class C Pin Mapping**
- **8-Channel ESD Lines for Four Differential Pairs with Ultra-low Differential Capacitance Matching (0.05pF)**
- **On-chip Load Switch with 55mA Current Limit Feature at the HDMI 5V_OUT Pin**
- **Auto-direction Sensing I²C Level Shifter with One-shot Circuit to Drive Long HDMI Cable (750pF Load)**
- **Back-drive Protection on HDMI Connector Side Ports**
- **Integrated Pull-up and Pull-down Resistors per HDMI Specification**
- **±8KV Contact Discharge Rating at all External Pins**
- **Space Saving 24-pin RKT Package and 24-TSSOP Package**

APPLICATIONS

- **Cell Phones**
- **eBook**
- **Portable Media Players**
- **Set-top Box**

DESCRIPTION

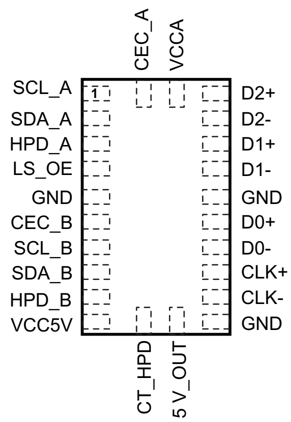
The TPD12S016 is a single-chip HDMI interface device with auto-direction sensing I2C voltage level shift buffers, load switch, and integrated high-speed ESD protection clamps. The device pin mapping matches the HDMI Type D connector with four differential pairs. This device offers eight low-capacitance ESD clamps, allowing HDMI 1.4 data rates. The integrated ESD circuits provide good matching between each differential signal pair, which allows an advantage over discrete ESD solutions where variations between ESD protection clamps degrade the differential signal quality. The TPD12S016 provides a current limited 5 V output (5V_OUT) for sourcing the HDMI power line. The current limited 5 V output supplies up to 55 mA to the HDMI receiver. The control of 5V_OUT and the hot plug detect (HPD) circuitry is independent of the LS_OE control signal, and is controlled by the CT_HPD pin. This independent CT_HPD control enables the detection scheme (5V_OUT and HPD) to be active before enabling the HDMI link. An internal 3.3V node powers the CEC pin eliminating the need for a 3.3V supply on board.

The TPD12S016 integrates all the external termination resistors at the HPD, CEC, SCL, and SDA lines. There are three non-inverting bi-directional translation circuits for the SDA, SCL, and CEC lines. Each have a common power rail (VCCA) on the A side from 1.1 V to 3.6V. On the B side, the SCL_B and SDA_B each have an internal 1.75 kΩ pull up connected to the 5 V rail (5V_OUT). The SCL and SDA pins meet the I2C specification and drive up to 750 pF capacitive loads exceeding the HDMI1.4 specifications. The CEC_B pin has an internal 27 kΩ pull up to the internal 3.3 V supply rail. The HPD_B port has a glitch filter to avoid false detection due to plug bouncing during the HDMI connector insertion.

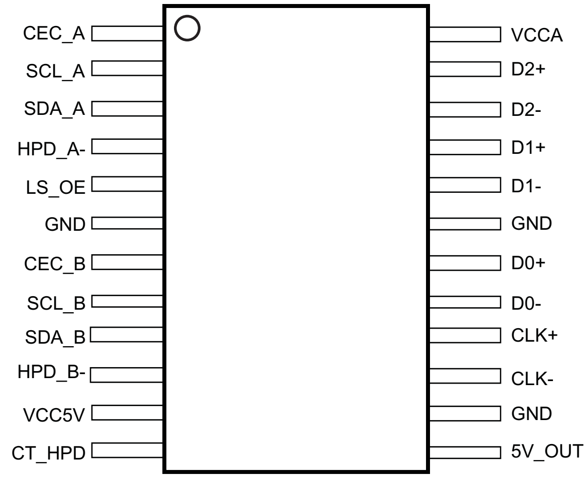
The TPD12S016 offers reverse current block feature at the 5V_OUT pin. In the fault conditions, such as when two HDMI transmitters connect to the same HDMI cable, the TPD12S016 ensures that the system is safe from powering up through external HDMI transmitter. The Dx, CLKx, SCL_B, SDA_B, CEC_B pins also feature reverse-current blocking when the system is powered off.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

PACKAGE INFORMATION



24-RKT Package (Top View)
(4.0mm x 2.0mm x 0.5mm)



24-PW Package (Top View)
(7.8mm x 6.1mm x 1.2mm)

APPLICATION INFORMATION

Application Case #1: HDMI Driver Chip is controlling the TPD12S016 via only one control line (CT_HPD). In this mode the HPD_A to LE_OE pin are connected as shown in the oval dotted line of Figure 1.

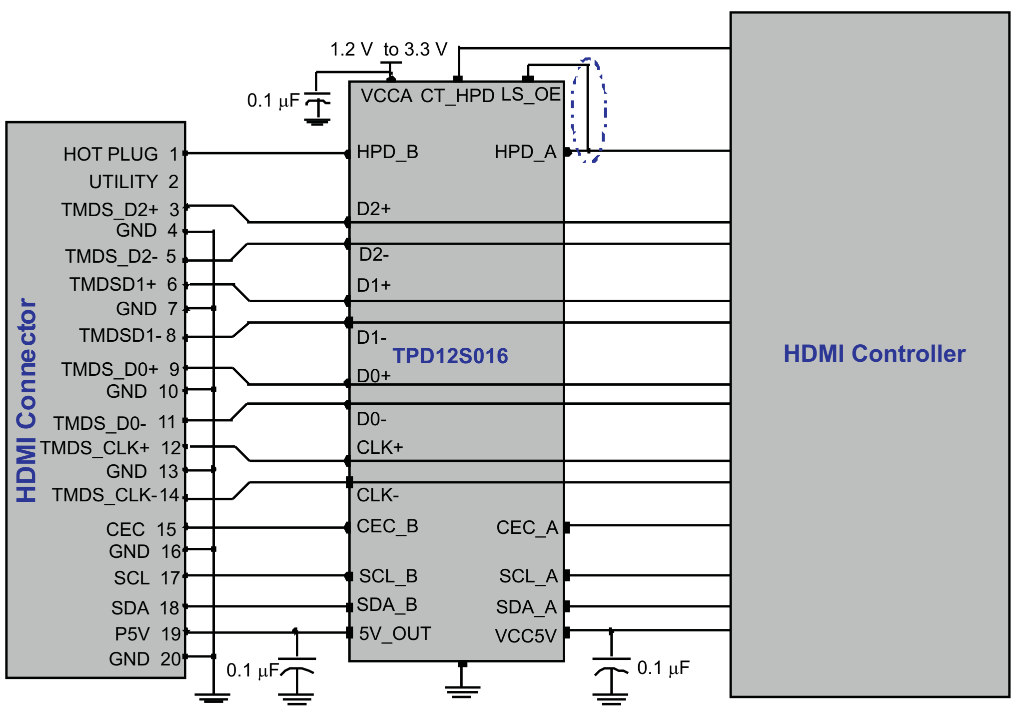


Figure 1. Application Schematics for HDMI Controllers with One GPIO for HDMI Interface Control

Application Case #2: Some HDMI driver chips may have two GPIOs to control the HDMI interface chip. In this case a flexible power saving mode can be implemented.

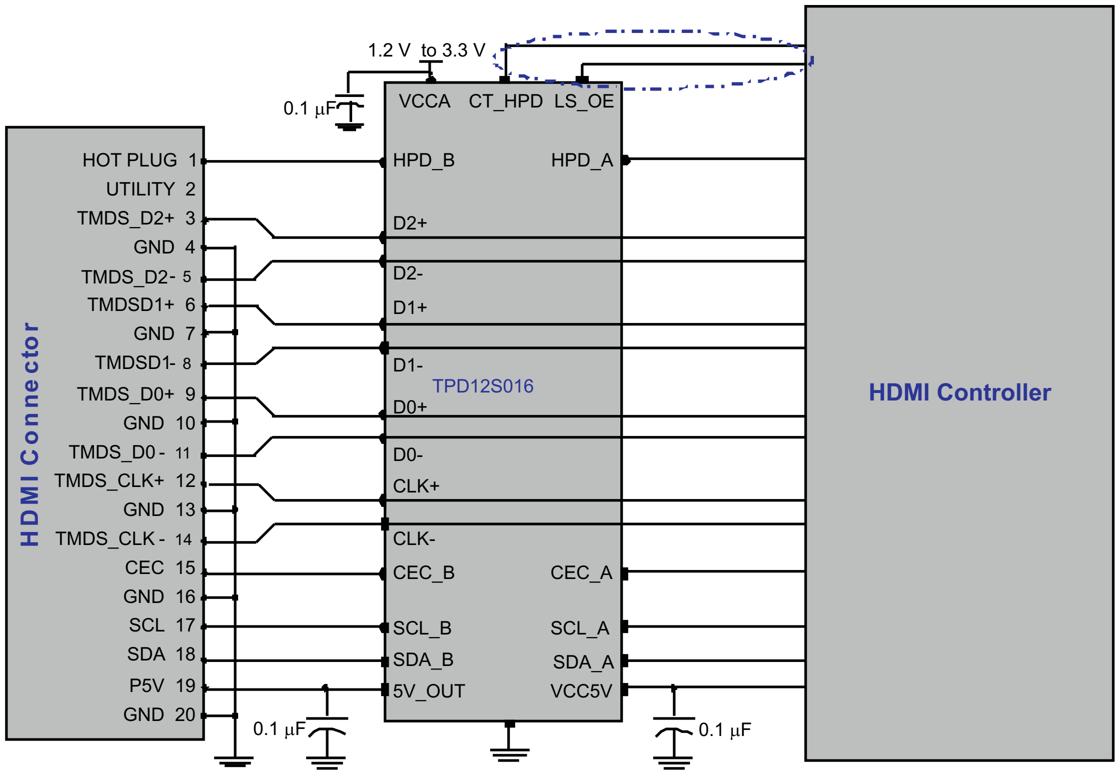


Figure 2. Application Schematics for HDMI Controllers with Two GPIOs for HDMI Interface Control

The LS_OE and CT_HPD are active-high enable pins. They control the TPD12S016 power saving options according to the following table:

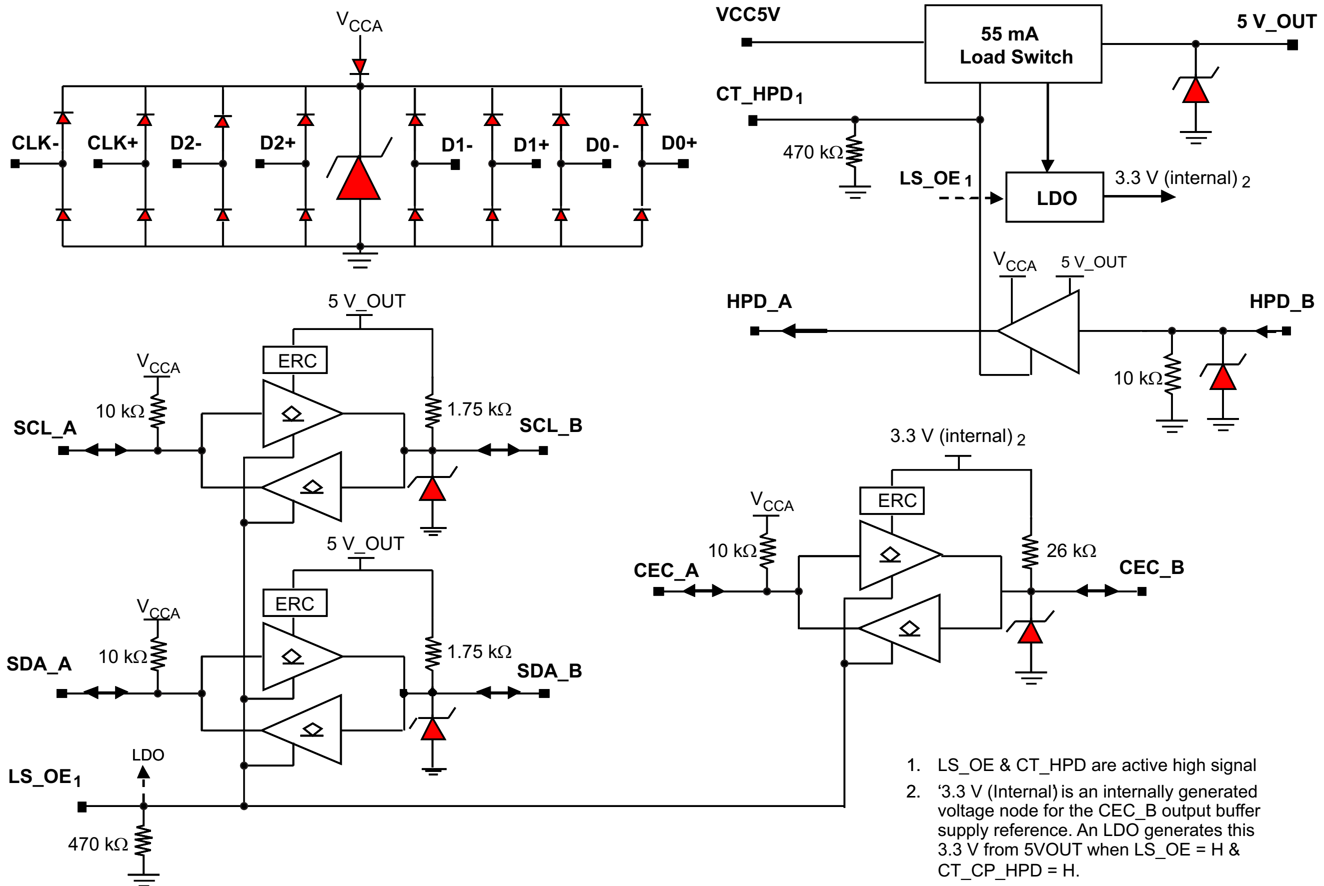
LS_OE	CT_HPD	VCCA	VCC5V	A-side Pull-ups	DDC, B-Side Pull-ups	CEC_B Pull-ups	CEC LDO	Load SW and HPD	DDC/ CEC VLTs	ICCA Typ	ICC5V Typ	Comments
L	L	1.8V	5.0V	Off	Off	Off	Off	Off	Off	1µA	1 µA	Fully Disabled
L	H	1.8V	5.0V	On	On	Off	Off	On	Off	1 µA	30 µA	Load Switch on
H	L	1.8V	5.0V	Off	Off	Off	Off	Off	Off	1 µA	1 µA	Not Valid State
H	H	1.8V	5.0V	On	On	On	On	On	On	13 µA	200 µA	Fully On
X	X	0V	0V	High-Z	High-Z	High-Z	Off	Off	Off	0	0	Power Down
X	X	1.8V	0V	High-Z	High-Z	High-Z	Off	Off	Off	0	0	Power Down
X	X	0V	5.0V	High-Z	High-Z	High-Z	Off	Off	Off	0	0	Power Down

ORDERING INFORMATION

T_A	PACKAGE(1)(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN –0.4-mm pitch (4.0mm x 2.0mm x 0.5mm)	Tape and reel	TPD12S016RKTR	PN016
	TSSOP –0.65-mm pitch (7.8mm x 6.4mm x 1.2mm)	Tape and reel	TPD12S016PWR	PN016

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

CIRCUIT SCHEMATIC DIAGRAM



PIN FUNCTIONS

PIN			PIN TYPE	DESCRIPTION
NAME	RKT	PW		
D–, D+	16, 17, 19-22	17, 18, 20-23	ESD Terminal	HDMI TMDS Data. Connect to HDMI Controller and HDMI Connector directly.
CLK–, CLK+	14, 15	15, 16	ESD Terminal	HDMI TMDS Clock. Connect to HDMI Controller and HDMI Connector directly.
HPD_A	3	4	Output	Hot plug detect Output referenced to VCCA. Connect to HDMI controller Hot plug detect input pin
HPD_B	9	10	Input	Hot plug detect Input. Connect directly to HDMI Connector Hot Plug Detect pin
CEC_A	24	1	IO Port	HDMI controller side CEC signal pin referenced to VCCA. Connect to HDMI controller.
CEC_B	6	7	IO Port	HDMI connector side CEC signal pin referenced to internal 3.3V supply. Connect to HDMI connector CEC pin.
SCL_A	1	2	IO Port	HDMI controller side SCL signal pin referenced to VCCA. Connect to HDMI controller.
SCL_B	7	8	IO Port	HDMI connector side SCL signal pin referenced to 5V_OUT supply. Connect to HDMI connector SCL pin.
SDA_A	2	3	IO Port	HDMI controller side SDA signal pin referenced to VCCA. Connect to HDMI controller.
SDA_B	8	9	IO Port	HDMI connector side SDA signal pin referenced to 5V_OUT supply. Connect to HDMI connector SDA pin.
LS_OE	4	5	Control Input	Disables the Level shifters when OE =L. The OE pin is referenced to VCCA
CT_HPD	11	12	Control Input	Disables the load switch and HPD_B when CT_HPD =L. The CT_HPD is referenced to VCCA
VCC5V	10	11	Input Power	Internal 5V Supply. (Input to the load siwtch.)
VCCA	23	24	Input Power	Internal PCB Low Voltage Supply (Same as the HDMI Controller Chip Supply)
5V_OUT	12	13	Output Power	External 5V Supply. (Output of the load switch.)
GND	5, 13, 18	6, 14, 19	Ground	Connect to System Ground Plane

ABSOLUTE MAXIMUM RATINGS(1)(2)

over operating free-air temperature range (unless otherwise noted)

			VALUE MIN	VALUE MAX	UNIT
V_{CCA}	Supply voltage range		–0.3	4.0	V
V_{CC5V}	Supply voltage range		–0.3	6.0	V
V_I	Input voltage range(2)	SCL_A, SDA_A, CEC_A	–0.3	4.0	V
		SCL_B, SDA_B, CEC_B	–0.3	6.0	
		CT_HPD, LS_OE	–0.3	4.0	
		D, CLK	–0.3	6.0	
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)	SCL_A, SDA_A, CEC_A, CT_HPD, LS_OE	–0.3	4.0	V
		SCL_B, SDA_B, CEC_B	–0.3	6.0	
V_O	Voltage range applied to any output in the high or low state(2)(3)	SCL_A, SDA_A, CEC_A, CT_HPD, LS_OE	–0.3	VCCA + 0.5	V
		SCL_B, SDA_B, CEC_B	–0.3	VCCB + 0.5	
I_{IK}	Input clamp current	VI < 0		–50	mA
I_{OK}	Output clamp current	VO < 0		–50	mA
	Continuous current through V_{CCB}, or GND			±100	mA
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
(2) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

over recommended operating free-air temperature range (unless otherwise noted)

				MIN	TYP	MAX	UNIT
V_{CCA}	Supply voltage			1.1		3.6	V
V_{CC5V}	Supply voltage			4.5		5.5	V
V_{IH}	High-level input voltage	SCL_A, SDA_A	VCCA =1.1V to 3.6 V	0.7×V_{CCA}		V_{CCA}	V
		CEC_A	VCCA =1.1V to 3.6 V	0.7×V_{CCA}		V_{CCA}	V
		CT__HPD, LS_OE	VCCA =1.1V to 3.6 V	1.0		V_{CCA}	V
		SCL_B, SDA_B	5V_OUT = 5.0 V	0.7×5V_OUT		5V_OUT	V
		CEC_B	5V_OUT = 5.0 V	0.7×V_{3P3}(1)		V_{3P3}	
		HPD_B	5V_OUT = 5.0 V	2.0		5V_OUT	
V_{IL}	Low-level input voltage	SCL_A, SDA_A	VCCA =1.1V to 3.6 V	–0.5		0.082×V_{CCA}	V
		CEC_A	VCCA =1.1V to 3.6 V	–0.5		0.082×V_{CCA}	V
		CT_HPD, LS_OE	VCCA =1.1V to 3.6 V	–0.5		0.4	V
		SCL_B, SDA_B	5V_OUT = 5.0 V	–0.5		0.3×5V_OUT	V
		CEC_B	5V_OUT = 5.0 V	–0.5		0.3×V_{3P3}	V
		HPD_B	5V_OUT = 5.0 V	0		0.8	V
V_{ILC}	(contention) Low-level input voltage	SCL_A, SDA_A, CEC_A	VCCA =1.1V to 3.6 V	–0.5		0.065×V_{CCA}	V
V_{OL} - V_{ILC}	Delta between V_{OL} and V_{ILC}	SCL_A, SDA_A, CEC_A	VCCA =1.1V to 3.6 V		0.1×V_{CCA}		mV
T_A	Operating free-air temperature			–40		85	°C

(1) The V3P3 is an internal 3.3V power supply node. The V3P3 is generated from the 5V supply pin through the on-chip LDO.

ESD TABLE

PARAMETER	SIGNALS	TYP	UNIT
HBM ESD	LS_OE, CT_HPD, SCL_A, SDA_A, CEC_A, HPD_A, VCCA	±2	kV
	Dx, CLKx, SCL_B, SDA_B, CEC_B, HPD_B , 5V_OUT	±15	kV
IEC 61000-4-2 Contact Discharge	Dx, CLKx, SCL_B, SDA_B, CEC_B, HPD_B , 5V_OUT	±8	kV

ELECTRICAL CHARACTERISTICS

High Speed ESD Lines: Dx, CLKx

PARAMETER			TEST CONDITION		MIN	TYP	MAX	UNIT
I_{IO}	Current through ESD clamp ports		V_{CCA} = 3.3 V, VCC5V = 5.0 V, V_{IO} = 3.3 V	D, CLK		0.01	0.5	µA
V_{DL}	Diode forward voltage		I_D = 8 mA	Lower clamp diode		0.8	1.0	V
R_{DYN}	Dynamic Resistance		I = 1 A	D, CLK		1		Ω
C_{IO}	IO capacitance	PW Package	V_{CC} = 5 V, V_{IO} = 2.5 V	D, CLK		1.0		pF
		RKT Package				1.2		
ΔC_{IO_TMDS}	Differential capacitance for the Dx+, Dx– lines		V_{CC} = 5 V, V_{IO} = 2.5 V	D, CLK		0.05		pF
V_{BR}	Break-down Voltage		I_{IO} = 1 mA		6.5		9	V

Load Switch VCC5V, 5V_OUT

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
I_{CC5V}	Supply current at VCC5V	VCC5V =5V, 5V OUT =Open, LS_OE = GND, CT_HPD = GND		1	45	µA
	Supply current at VCC5V	VCC5V =5V, 5V OUT =Open, LS_OE = GND, CT_HPD = 3.3V		4	50	µA
I_{SC}	Short circuit current at 5V_OUT	VCC5V =5V, 5V_OUT = GND	100	150	200	mA
V_{DROP}	5V_OUT output voltage drop	VCC5V =5V, I_{5V_OUT} = 55 mA		35	50	mV
T_{ON}	Turn on Time, VCC5V to 5V_OUT	C_{LOAD} = 0.1µF, R_{LOAD} = 500Ω		77		µs
T_{OFF}	Turn off Time, VCC5V to 5V_OUT	C_{LOAD} = 0.1µF, R_{LOAD} = 500Ω		7.0		µs
T_{SHUT}	Thermal Shutdown	Shutdown threshold, TRIP (1)		140		°C
		HYST (2)		12		

(1) The TPD12S016 turns off after the device temperature reaches the TRIP temperature.
(2) Once the thermal shut-down circuit turns off the load switch, the switch turns on again after the device junction temperature cools down to a temperature equals to or less than TRIP-HYST.

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B Ports)

PARAMETER		TEST CONDITIONS		V_{CCA}	–40°C to 85°C			UNIT
					MIN	TYP	MAX	
V_{OHA}		I_{OH} = –20 µA	$V_I = V_{IH}$	1.1 V to 3.6 V	V_{CCA} ×0.80			V
V_{OLA}		I_{OL} = 20 µA	$V_I = V_{IL}$	1.1 V to 3.6 V		V_{CCA} ×0.17		V
V_{OHB}		I_{OH} = –20 µA	$V_I = V_{IH}$		5VOUT ×0.90			V
V_{OLB}		I_{OL} = 3 mA	$V_I = V_{IL}$				0.4	V
ΔV_T	Hysteresis at the SDx_A ($V_{T+} - V_{T-}$)			1.1 V to 3.6 V		40		mV
ΔV_T	Hysteresis at the SDx_B ($V_{T+} - V_{T-}$)			1.1 V to 3.6 V		400		mV
R_{PU}	(Internal pull-up)	SCL_A, SDA_A	Pull-up connected to VCCA rail			10		kΩ
		SCL_B, SDA_B	Pull-up connected to 5 V rail			1.75		
$I_{PULLUP\ AC}$	Transient boosted pull-up current (rise-time accelerator)	SCL_B, SDA_B	Pull-up connected to 5 V rail			15		mA
I_{off}	A port	VCCA = 0 V, V_I or V_O = 0 to 3.6 V		0 V			±5	µA
	B port	5VOUT = 0 V, V_I or V_O = 0 to 5.5 V		0 V to 3.6 V			±5	
I_{OZ}	B port	$V_O = V_{CCO}$ or GND		1.1 V to 3.6 V			±5	µA
	A port	$V_I = V_{CCI}$ or GND		1.1 V to 3.6 V			±5	

Voltage Level Shifter – CEC Line (x_A and x_B ports)

PARAMETER		TEST CONDITIONS		V_{CCA}	–40°C to 85°C MIN	TYP	MAX	UNIT
V_{OHA}		I_{OH} = –20 µA	$V_I = V_{IH}$	1.1 V to 3.6 V	V_{CCA} ×0.80			V
V_{OLA}		I_{OL} = 20 µA	$V_I = V_{IL}$	1.1 V to 3.6 V			V_{CCA} ×0.17	V
V_{OHB}		I_{OH} = –20 µA	$V_I = V_{IH}$		V_{3P3} ×0.80			V
V_{OLB}		I_{OL} = 3 mA	$V_I = V_{IL}$				0.4	V
ΔV_T	Hysteresis at the Sxx_A ($V_{T+} – V_{T–}$)			1.1 V to 3.6 V		40		mV
ΔV_T	Hysteresis at the Sxx_B ($V_{T+} – V_{T–}$)			1.1 V to 3.6 V		300		mV
R_{PU}	(Internal pull-up)	CEC_A	Pull-up connected to VCCA rail			10		kΩ
		CEC_B	Pull-up connected to 3.3 V rail		22	26	30	
I_{off}	A port	VCCA = 0 V, V_I or V_O = 0 to 3.6 V		0 V			±5	µA
	B port	5VOUT = 0 V, V_I or V_O = 0 to 5.5 V		0 V to 3.6 V			±1.8	
I_{OZ}	B port	$V_O = V_{CCO}$ or GND		1.1 V to 3.6 V			±5	µA
	A port	$V_I = V_{CCI}$ or GND		1.1 V to 3.6 V			±5	

Voltage Level Shifter – HPD Line (x_A and x_B ports)

PARAMETER		TEST CONDITIONS		V_{CCA}	–40°C to 85°C MIN	TYP	MAX	UNIT
V_{OHA}		I_{OH} = –3 mA	$V_I = V_{IH}$	1.1 V to 3.6 V	V_{CCA} ×0.07			V
V_{OLA}		I_{OL} = 3 mA	$V_I = V_{IL}$	1.1 V to 3.6 V			0.4	V
ΔV_T	Hysteresis ($V_{T+} – V_{T–}$)			1.1 V to 3.6 V		400		mV
R_{PD}	(Internal pull-down resistor)	HPD_B	Pull-down connected to GND			11		kΩ
I_{off}	A port	$V_O = V_{CCO}$ or GND		0 V			±5	µA
I_{OZ}	A port	$V_I = V_{CCO}$ or GND		3.6 V			±5	µA

LS_OE, CT_CP_HPD

PARAMETER	TEST CONDITIONS	V_{CCA}	–40°C to 85°C MIN	TYP	MAX	UNIT
I_I	$V_I = V_{CCA}$ or GND	1.1 V to 3.6 V			±12	µA

I/O Capacitances

PARAMETER		TEST CONDITIONS	V_{CCA}	–40°C to 85°C MIN	TYP	MAX	UNIT
C_I	Control inputs	V_I = 1.89 V or GND	1.1 V to 3.6 V		7.1		pF
C_{io}	A port	V_O = 1.89 V or GND	1.1 V to 3.6 V		8.3		pF
	B port	V_O = 5.0 V or GND	5.0 V		15		pF

SWITCHING CHARACTERISTICS

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_L	Bus Load Capacitance (B Side)				750	pF
	Bus Load Capacitance (A Side)				15	

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B ports) VCCA = 1.2 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	SCL/SDA Channels Enabled		310		nS
		B to A	SCL/SDA Channels Enabled		420		
t_{PLH}	Propagation delay	A to B	SCL/SDA Channels Enabled		510		nS
		B to A	SCL/SDA Channels Enabled		427		
t_{FALL}	A Port fall time	A-Port	SCL/SDA Channels Enabled		334		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		225		
t_{RISE}	A Port rise time	A-Port	SCL/SDA Channels Enabled		315		nS
	B Port rise time	B-Port	SCL/SDA Channels Enabled		415		
$F_{(MAX)}$	Maximum switching frequency		SCL/SDA Channels Enabled	400			kHz

Voltage Level Shifter – CEC Lines (x_A and x_B ports) VCCA = 1.2 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	CEC Channel Enabled		385		nS
		B to A	CEC Channel Enabled		526		
t_{PLH}	Propagation delay	A to B	CEC Channel Enabled		13.8		µS
		B to A	CEC Channel Enabled		16.6		nS
t_{FALL}	A Port fall time	A-Port	CEC Channel Enabled		334		nS
	B Port fall time	B-Port	CEC Channel Enabled		170		
t_{RISE}	A Port rise time	A-Port	CEC Channel Enabled		315		nS
	B Port rise time	B-Port	CEC Channel Enabled		28		µS

Voltage Level Shifter – HPD Lines (x_A and x_B ports) VCCA = 1.2 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	B to A	HPD Channel Enabled		14.4		µS
t_{PLH}	Propagation delay	B to A	HPD Channel Enabled		9.2		µS
t_{FALL}	A Port fall time	A-Port	HPD Channel Enabled		2.1		nS
t_{RISE}	A Port rise time	A-Port	HPD Channel Enabled		2.1		nS

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B ports) VCCA = 1.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	SCL/SDA Channels Enabled		310		nS
		B to A	SCL/SDA Channels Enabled		420		nS
t_{PLH}	Propagation delay	A to B	SCL/SDA Channels Enabled		410		nS
		B to A	SCL/SDA Channels Enabled		425		nS
t_{FALL}	A Port fall time	A-Port	SCL/SDA Channels Enabled		250		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		225		nS
t_{RISE}	A Port rise time	A-Port	SCL/SDA Channels Enabled		315		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		415		nS
$F_{(MAX)}$	Maximum switching frequency		SCL/SDA Channels Enabled	400			kHz

Voltage Level Shifter – CEC Lines (x_A and x_B ports) VCCA = 1.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	CEC Channel Enabled		380		nS
		B to A	CEC Channel Enabled		420		
t_{PLH}	Propagation delay	A to B	CEC Channel Enabled		13.8		µS
		B to A	CEC Channel Enabled		16.6		nS
t_{FALL}	A Port fall time	A-Port	CEC Channel Enabled		250		nS
	B Port fall time	B-Port	CEC Channel Enabled		170		
t_{RISE}	A Port rise time	A-Port	CEC Channel Enabled		315		nS
	B Port rise time	B-Port	CEC Channel Enabled		28		µS

Voltage Level Shifter – HPD Lines (x_A and x_B ports) VCCA = 1.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	B to A	HPD Channel Enabled		14.4		µS
t_{PLH}	Propagation delay	B to A	HPD Channel Enabled		9.2		µS
t_{FALL}	A Port fall time	A-Port	HPD Channel Enabled		1.8		nS
t_{RISE}	A Port rise time	A-Port	HPD Channel Enabled		1.8		nS

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B ports) VCCA = 1.8 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	SCL/SDA Channels Enabled		300		nS
		B to A	SCL/SDA Channels Enabled		350		nS
t_{PLH}	Propagation delay	A to B	SCL/SDA Channels Enabled		400		nS
		B to A	SCL/SDA Channels Enabled		420		nS
t_{FALL}	A Port fall time	A-Port	SCL/SDA Channels Enabled		210		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		225		nS
t_{RISE}	A Port rise time	A-Port	SCL/SDA Channels Enabled		315		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		415		nS
$F_{(MAX)}$	Maximum switching frequency		SCL/SDA Channels Enabled	400			kHz

Voltage Level Shifter – CEC Lines (x_A and x_B ports) VCCA = 1.8 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	CEC Channel Enabled		375		nS
		B to A	CEC Channel Enabled		366		
t_{PLH}	Propagation delay	A to B	CEC Channel Enabled		13.8		µS
		B to A	CEC Channel Enabled		16.6		nS
t_{FALL}	A Port fall time	A-Port	CEC Channel Enabled		210		nS
	B Port fall time	B-Port	CEC Channel Enabled		170		
t_{RISE}	A Port rise time	A-Port	CEC Channel Enabled		315		nS
	B Port rise time	B-Port	CEC Channel Enabled		28		µS

Voltage Level Shifter – HPD Lines (x_A and x_B ports) VCCA = 1.8 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	B to A	HPD ChannelsEnabled		14.2		µS
t_{PLH}	Propagation delay	B to A	HPD Channel Enabled		9.2		µS
t_{FALL}	A Port fall time	A-Port	HPD Channel Enabled		1.5		nS
t_{RISE}	A Port rise time	A-Port	HPD Channel Enabled		1.5		nS

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B ports) VCCA = 2.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	SCL/SDA Channels Enabled		300		nS
		B to A	SCL/SDA Channels Enabled		400		nS
t_{PLH}	Propagation delay	A to B	SCL/SDA Channels Enabled		290		nS
		B to A	SCL/SDA Channels Enabled		420		nS
t_{FALL}	A Port fall time	A-Port	SCL/SDA Channels Enabled		170		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		225		nS
t_{RISE}	A Port rise time	A-Port	SCL/SDA Channels Enabled		315		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		415		nS
$F_{(MAX)}$	Maximum switching frequency		SCL/SDA Channels Enabled	400			kHz

Voltage Level Shifter – CEC Lines (x_A and x_B ports) VCCA = 2.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	CEC Channel Enabled		375		nS
		B to A	CEC Channel Enabled		305		
t_{PLH}	Propagation delay	A to B	CEC Channel Enabled		13.8		µS
		B to A	CEC Channel Enabled		16.6		nS
t_{FALL}	A Port fall time	A-Port	CEC Channel Enabled		170		nS
	B Port fall time	B-Port	CEC Channel Enabled		170		
t_{RISE}	A Port rise time	A-Port	CEC Channel Enabled		315		nS
	B Port rise time	B-Port	CEC Channel Enabled		28		µS

Voltage Level Shifter – HPD Lines (x_A and x_B ports) VCCA = 2.5 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	B to A	HPD Channel Enabled		14.2		µS
t_{PLH}	Propagation delay	B to A	HPD Channel Enabled		9.2		µS
t_{FALL}	A Port fall time	A-Port	HPD Channel Enabled		1.2		nS
t_{RISE}	A Port rise time	A-Port	HPD Channel Enabled		1.2		nS

Voltage Level Shifter – SCL, SDA Lines (x_A and x_B ports) VCCA = 3.3 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	SCL/SDA Channels Enabled		300		nS
		B to A	SCL/SDA Channels Enabled		400		nS
t_{PLH}	Propagation delay	A to B	SCL/SDA Channels Enabled		260		nS
		B to A	SCL/SDA Channels Enabled		415		nS
t_{FALL}	A Port fall time	A-Port	SCL/SDA Channels Enabled		160		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		225		nS
t_{RISE}	A Port rise time	A-Port	SCL/SDA Channels Enabled		305		nS
	B Port fall time	B-Port	SCL/SDA Channels Enabled		415		nS
$F_{(MAX)}$	Maximum switching frequency		SCL/SDA Channels Enabled	400			kHz

Voltage Level Shifter – CEC Lines (x_A and x_B ports) VCCA = 3.3 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	A to B	CEC Channel Enabled		375		nS
		B to A	CEC Channel Enabled		305		
t_{PLH}	Propagation delay	A to B	CEC Channel Enabled		13.8		µS
		B to A	CEC Channel Enabled		16.6		nS
t_{FALL}	A Port fall time	A-Port	CEC Channel Enabled		160		nS
	B Port fall time	B-Port	CEC Channel Enabled		170		
t_{RISE}	A Port rise time	A-Port	CEC Channel Enabled		305		nS
	B Port rise time	B-Port	CEC Channel Enabled		28		µS

Voltage Level Shifter – HPD Lines (x_A and x_B ports) VCCA = 3.3 V

PARAMETER		PINS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay	B to A	HPD Channel Enabled		14.2		µS
t_{PLH}	Propagation delay	B to A	HPD Channel Enabled		9.2		µS
t_{FALL}	A Port fall time	A-Port	HPD Channel Enabled		1.1		nS
t_{RISE}	A Port rise time	A-Port	HPD Channel Enabled		1.1		nS

APPLICATION INFORMATION

DDC/CEC LEVEL SHIFT Circuit Operation

The TPD12S016 enables DDC translation from VCCA (system side) voltage levels to 5V (HDMI cable side) voltage levels without degradation of system performance. The TPD12S016 contains 2 bidirectional open-drain buffers specifically designed to support up-translation/down-translation between the low voltage, VCCA side DDC-bus and the 5V DDC-bus. The port B I/Os are over-voltage tolerant to 5.5 V even when the device is un-powered. After power-up and with the LS_OE and CT_HPD pins HIGH, a LOW level on port A (below approximately V_{ILC} = 0.08×VCCA V) turns the corresponding port B driver (either SDA or SCL) on and drives port B down to V_{OLB} V. When port A rises above approximately 0.10×VCCA V, the port B pull-down driver is turned off and the internal pull-up resistor pulls the pin HIGH. When port B falls first and goes below 0.3×5VOUT, a CMOS hysteresis input buffer detects the falling edge, turns on the port A driver, and pulls port A down to approximately VOLA=0.16×VCCA V. The port B pull-down is not enabled unless the port A voltage goes below V_{ILC}. If the port A low voltage goes below V_{ILC}, the port B pull-down driver is enabled until port A rises above (V_{ILC} + $\Delta V_{T\text{-}HYSTA}$), then port B, if not externally driven LOW, will continue to rise being pulled up by the internal pull-up resistor.

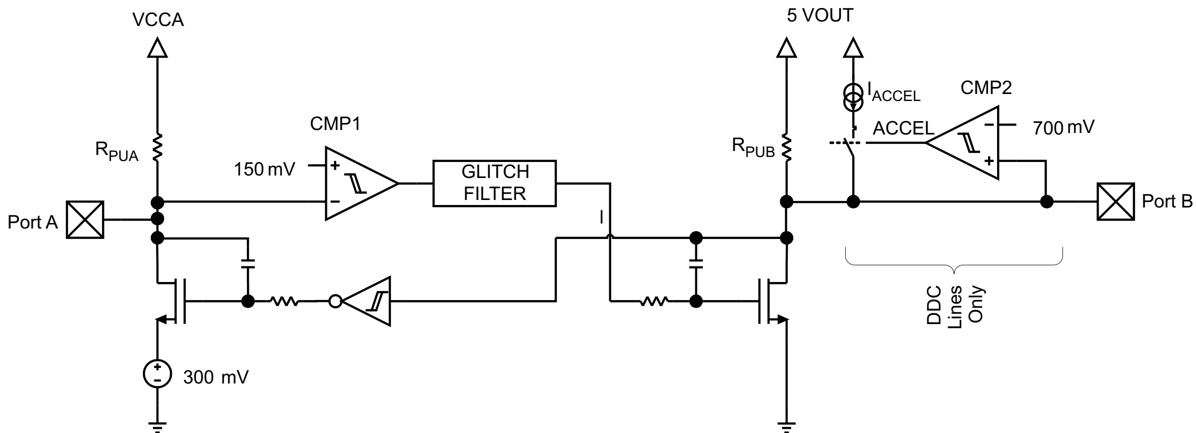


Figure 3. DDC/CEC Level Shifter Block Diagram

DDC/CEC Level Shifter Operational Notes for VCCA=1.8V

- The threshold of CMP1 is ~150mV ± the 40mV of total hysteresis.
- The comparator will trip for a falling waveform at ~130mV
- The comparator will trip for a rising waveform at ~170mV
- To be recognized as a zero, the level at Port A must first go below 130mV (V_{ILC} in spec) and then stay below 170mV (V_{ILA} in spec)
- To be recognized as a one, the level at A must first go above 170mV and then stay above 130mV
- V_{ILC} is set to 110mV in Electrical Characteristics Table to give some margin to the 130mV
- V_{ILA} is set to 140mV in the Electrical Characteristics Table to give some margin to the 170mV
- V_{IHA} is set to 70% of VCCA to be consistent with standard CMOS levels

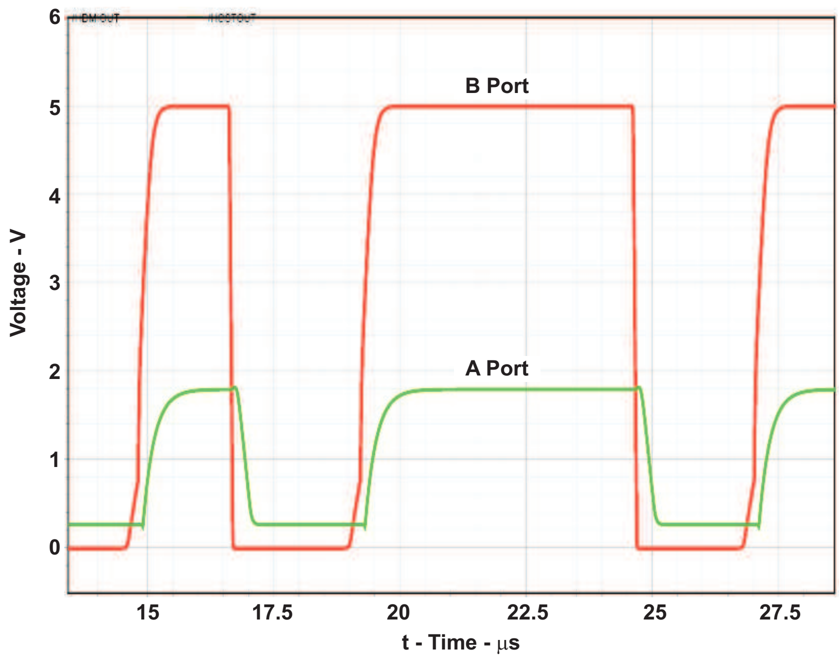


Figure 4. DDC Level Shifter Operation (B to A Direction)

Rise-Time Accelerators

The HDMI cable side of the DDC lines incorporates rise-time accelerators to support the high capacitive load on the HDMI cable side. The rise time accelerator boosts the cable side DDC signal independent of which side of the bus is releasing the signal.

Noise Considerations:

Ground offset between the TPD12S016 ground and the ground of devices on port A of the TPD12S016 must be avoided. The reason for this cautionary remark is that a CMOS/NMOS open-drain capable of sinking 3 mA of current at 0.4 V will have an output resistance of 133 Ω or less (R = E / I). Such a driver will share enough current with the port A output pull-down of the TPD12S016 to be seen as a LOW as long as the ground offset is zero. If the ground offset is greater than 0 V, then the driver resistance must be less. Since V_{ILC} can be as low as 90 mV at cold temperatures and the low end of the current distribution, the maximum ground offset should not exceed 50 mV. Bus repeaters that use an output offset are not interoperable with the port A of the TPD12S016 as their output LOW levels will not be recognized by the TPD12S016 as a LOW. If the TPD12S016 is placed in an application where the VIL of port A of the TPD12S016 does not go below its V_{ILC} it will pull port B LOW initially when port A input transitions LOW but the port B will return HIGH, so it will not reproduce the port A input on port B. Such applications should be avoided. Port B is interoperable with all I2C-bus slaves, masters and repeaters.

Resistor Pull-Up Value Selection

The system is designed to work properly with no external pull-up resistors on the DDC, CEC, and HPD lines.

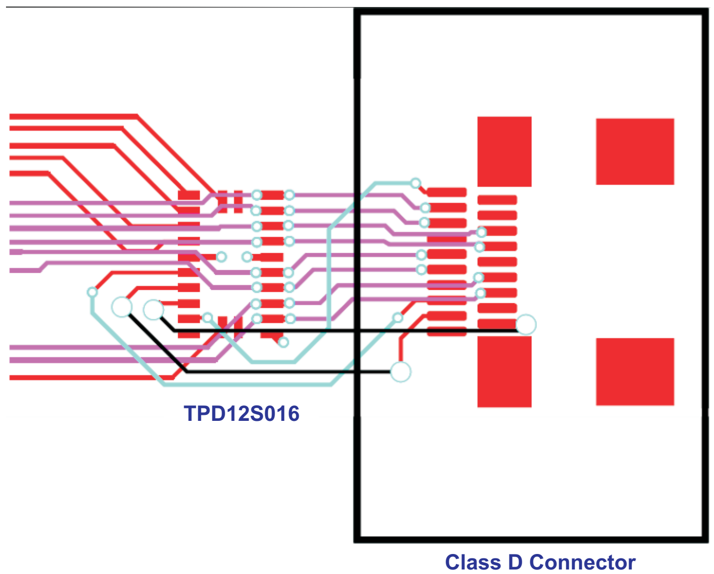


Figure 5. Board Layout for RKT Package

TYPICAL CHARACTERISTICS

IEC CLAMPING WAVEFORM +8kV CONTACT

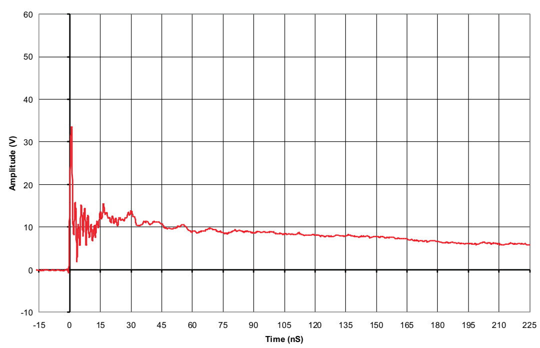


Figure 6.

IEC CLAMPING WAVEFORM –8kV CONTACT

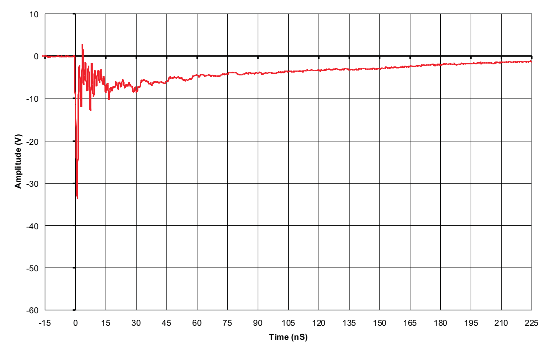


Figure 7.

CT_HPD V_{TH}

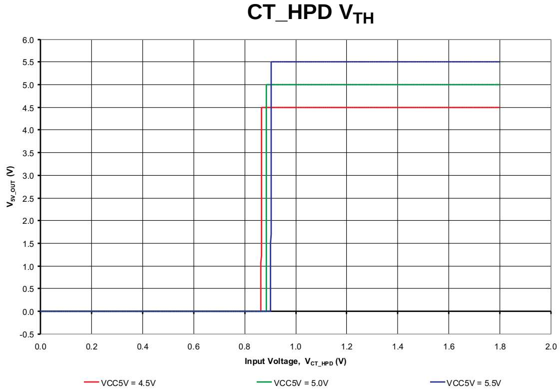


Figure 8.

INSERTION LOSS, DATA LINE TO GND

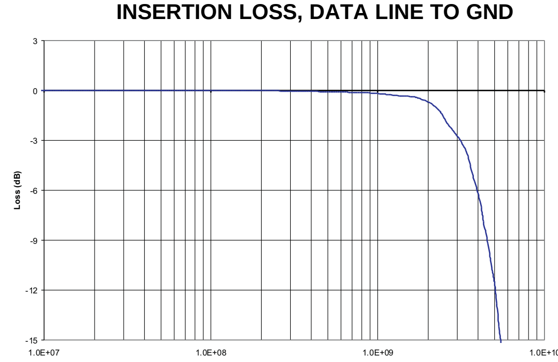


Figure 9.

CHANNEL-TO-CHANNEL CROSSTALK

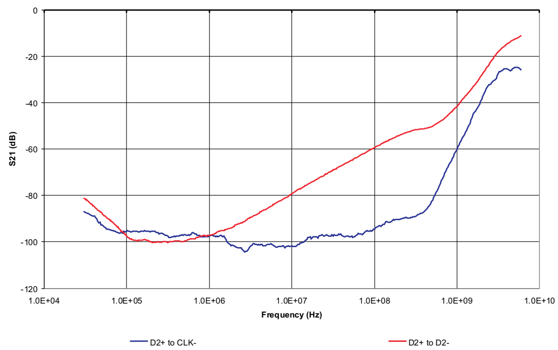


Figure 10.

SWITCH RESISTANCE vs TEMPERATURE
I_{SWITCH} ~ 55mA

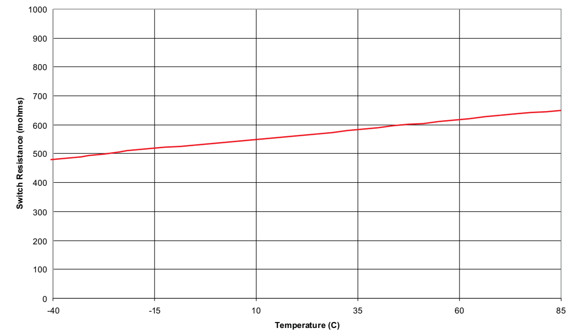


Figure 11.

LOAD SWITCH $I_{LEAKAGE}$ vs TEMPERATURE

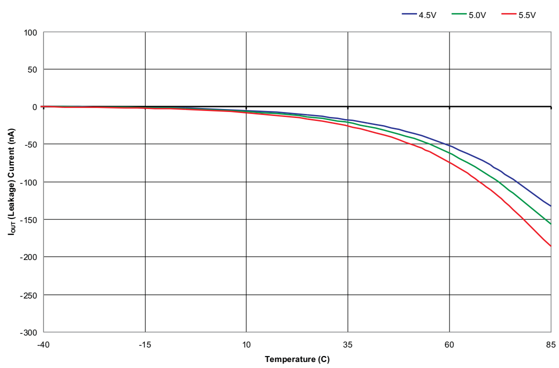


Figure 12.

TMDS LINE I_{IO} vs TEMPERATURE

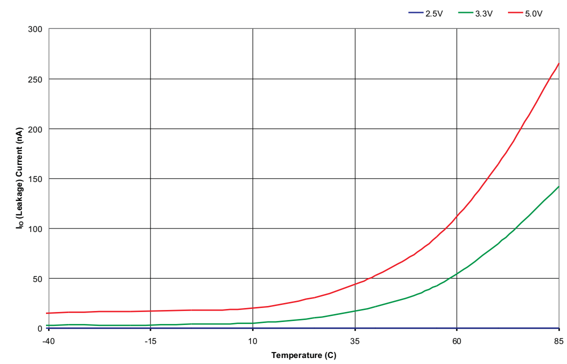


Figure 13.

SHORT-CIRCUIT RESPONSE TIME
(POWERED-UP TO SHORT)

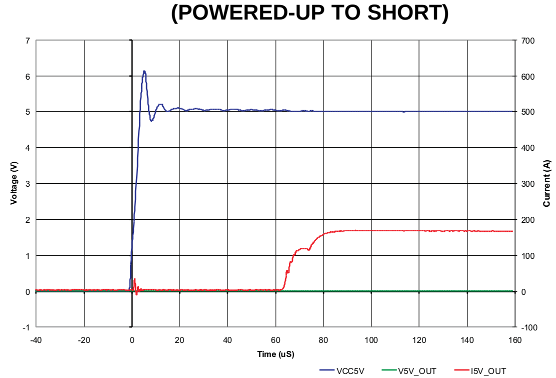


Figure 14.

CURRENT LIMIT RESPONSE TIME
(SWITCH ENABLED TO SHORT)

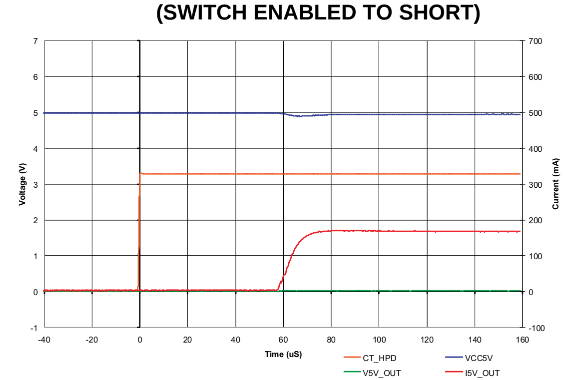


Figure 15.

CAPACITANCE vs BIAS VOLTAGE

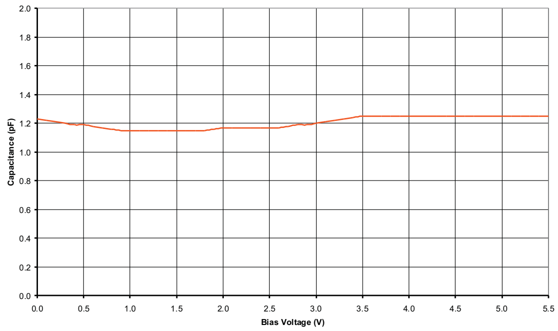


Figure 16.

LOAD SWITCH $I_{LEAKAGE\_REVERSE}$ vs V_{5V_OUT}

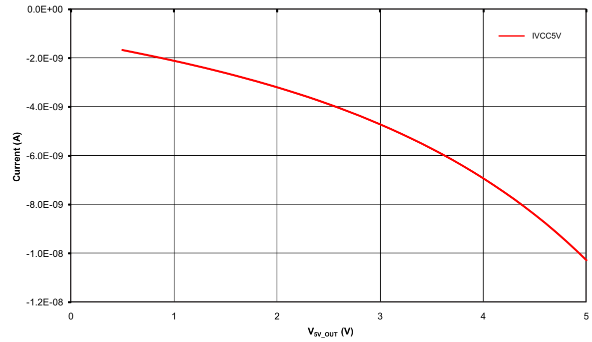


Figure 17.

Eye Diagram Using EVM Without TPD12S016 for the TMDS Lines at 1080p, 340MHz Pixel Clock, 3.4Gbps

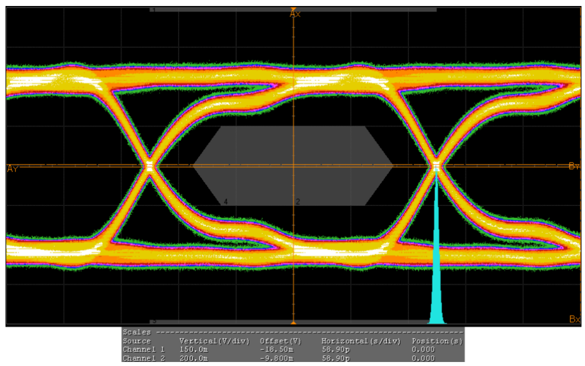


Figure 18.

Eye Diagram Using EVM with TPD12S016 for the TMDS Lines at 1080p, 340MHz Pixel Clock, 3.4Gbps

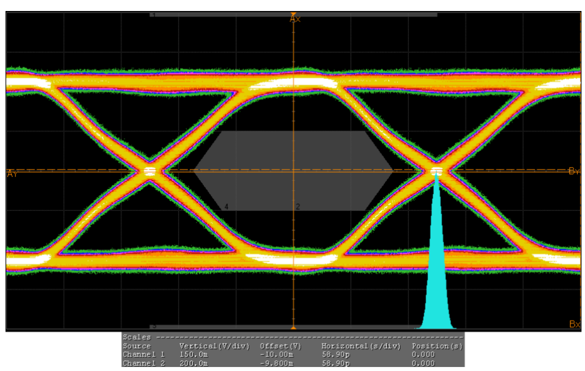


Figure 19.

REVISION HISTORY

Changes from Original (September 2011) to Revision A	Page
• Added Eye Diagram Using EVM Without TPD12S016 for the TMDS Lines at 1080p, 340MHz Pixel Clock, 3.4Gbps	17
• Added Eye Diagram Using EVM with TPD12S016 for the TMDS Lines at 1080p, 340MHz Pixel Clock, 3.4Gbps	17

Changes from Revision A (October 2011) to Revision B	Page
• Updated Circuit Schematic Diagram.	4
• Added PW and RKT packages values for IO capacitance.	6
• Added LOAD SWITCH $I_{LEAKAGE\_REVERSE}$ vs V_{5V_OUT} graph.	16

Changes from Revision B (June 2012) to Revision C	Page
• Updated table formatting.	6

Changes from Revision C (July 2012) to Revision D	Page
• Updated power savings options table.	3
• Clarified CLK pin orientation.	4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
HPA02285RKTR	ACTIVE	UQFN	RKT	24	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PN016	Samples
TPD12S016PWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PN016	Samples
TPD12S016RKTR	ACTIVE	UQFN	RKT	24	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PN016	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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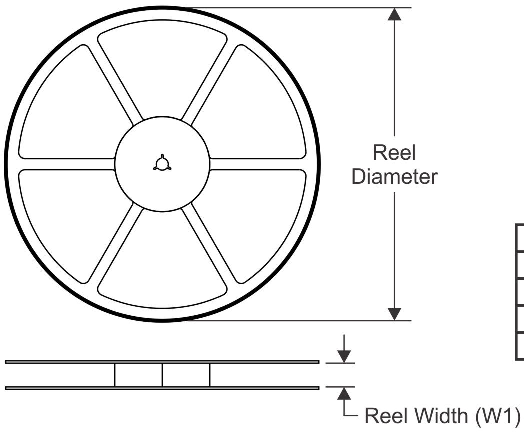
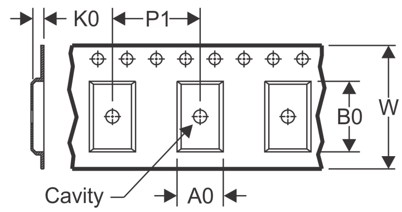
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

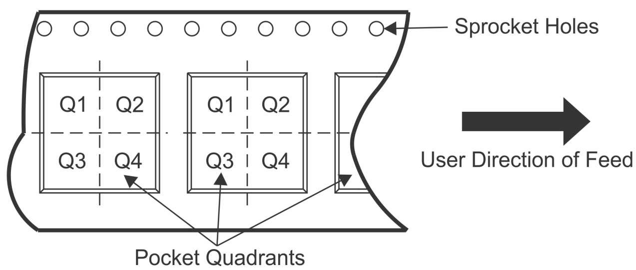


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

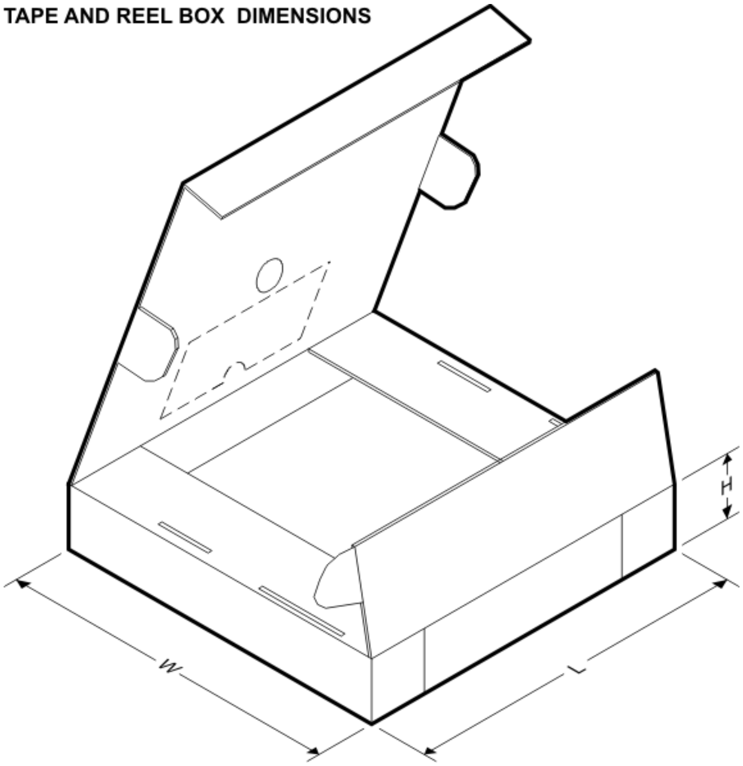
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD12S016PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
TPD12S016RKTR	UQFN	RKT	24	3000	177.8	12.4	2.21	4.22	0.81	4.0	12.0	Q1

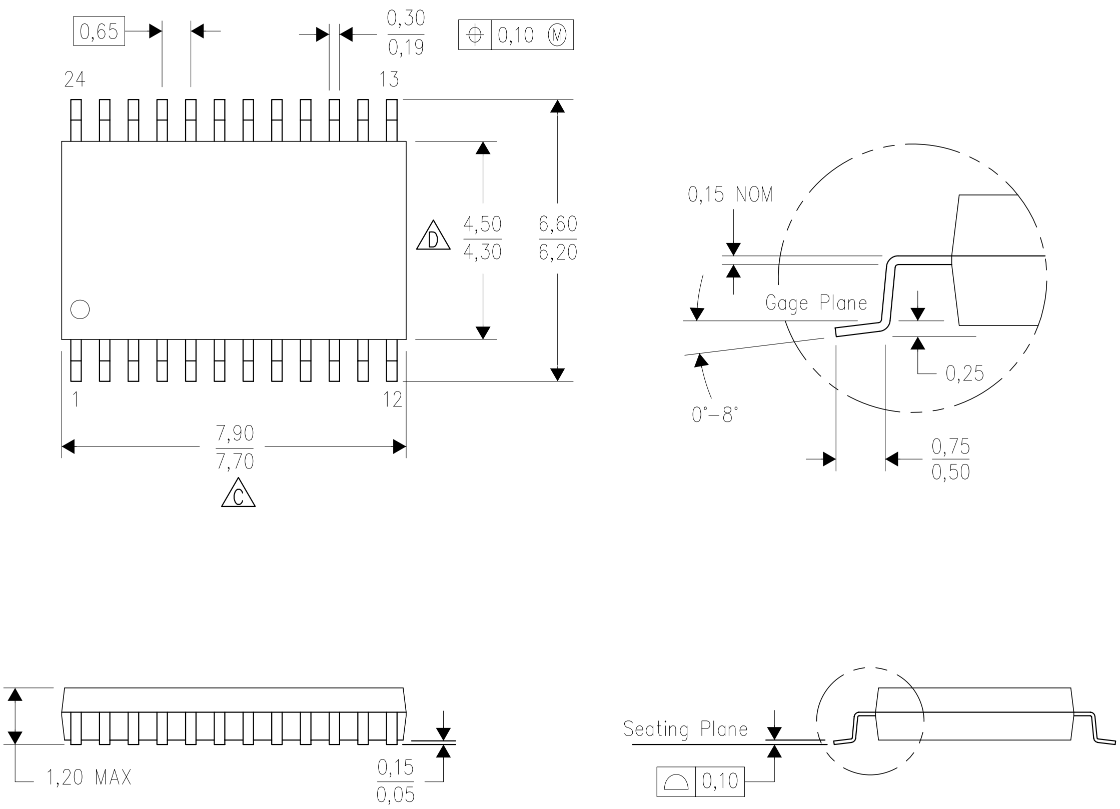
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD12S016PWR	TSSOP	PW	24	2000	367.0	367.0	38.0
TPD12S016RKTR	UQFN	RKT	24	3000	202.0	201.0	28.0

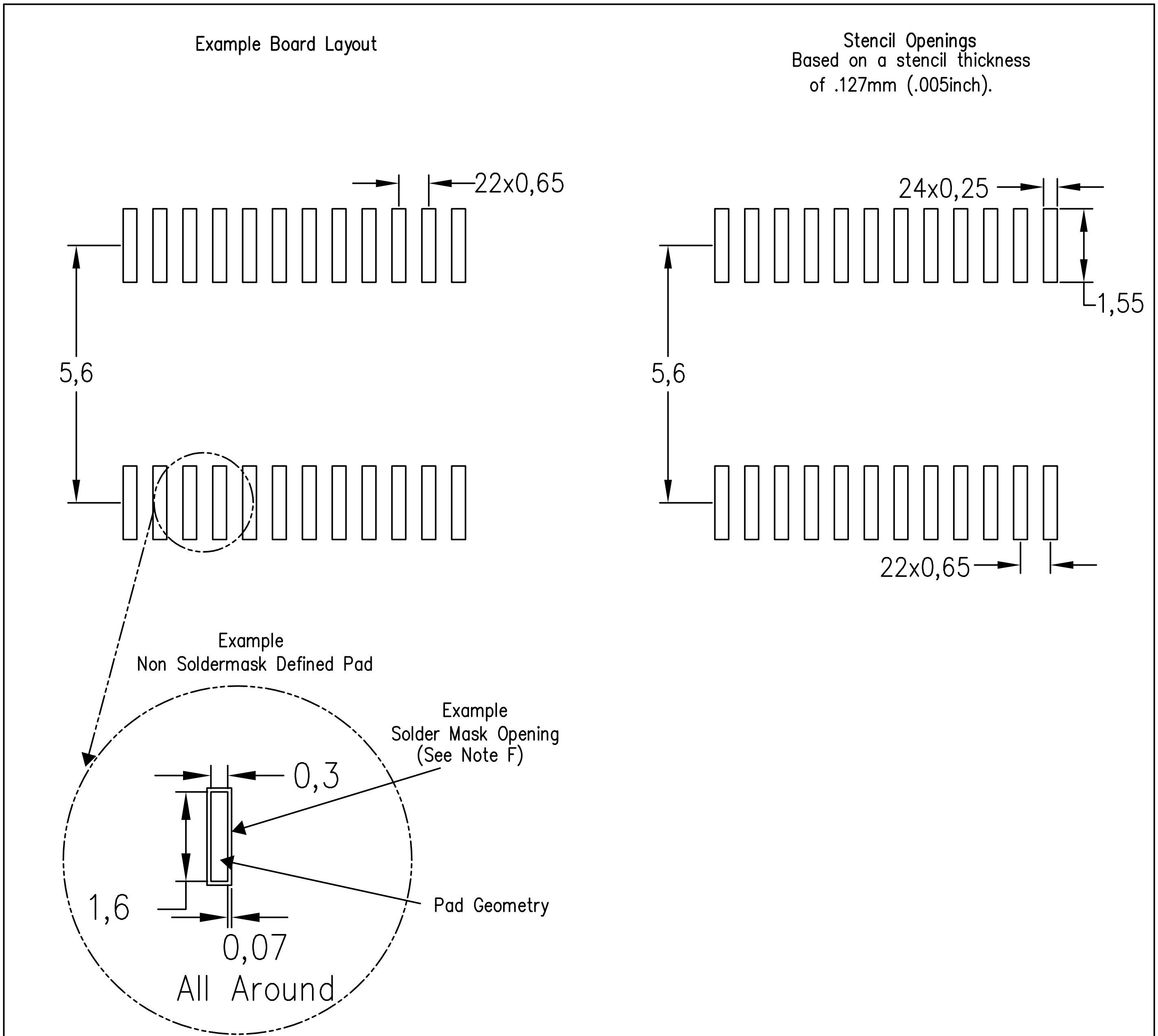
PW (R-PDSO-G24) PLASTIC SMALL OUTLINE



4040064-6/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO-153

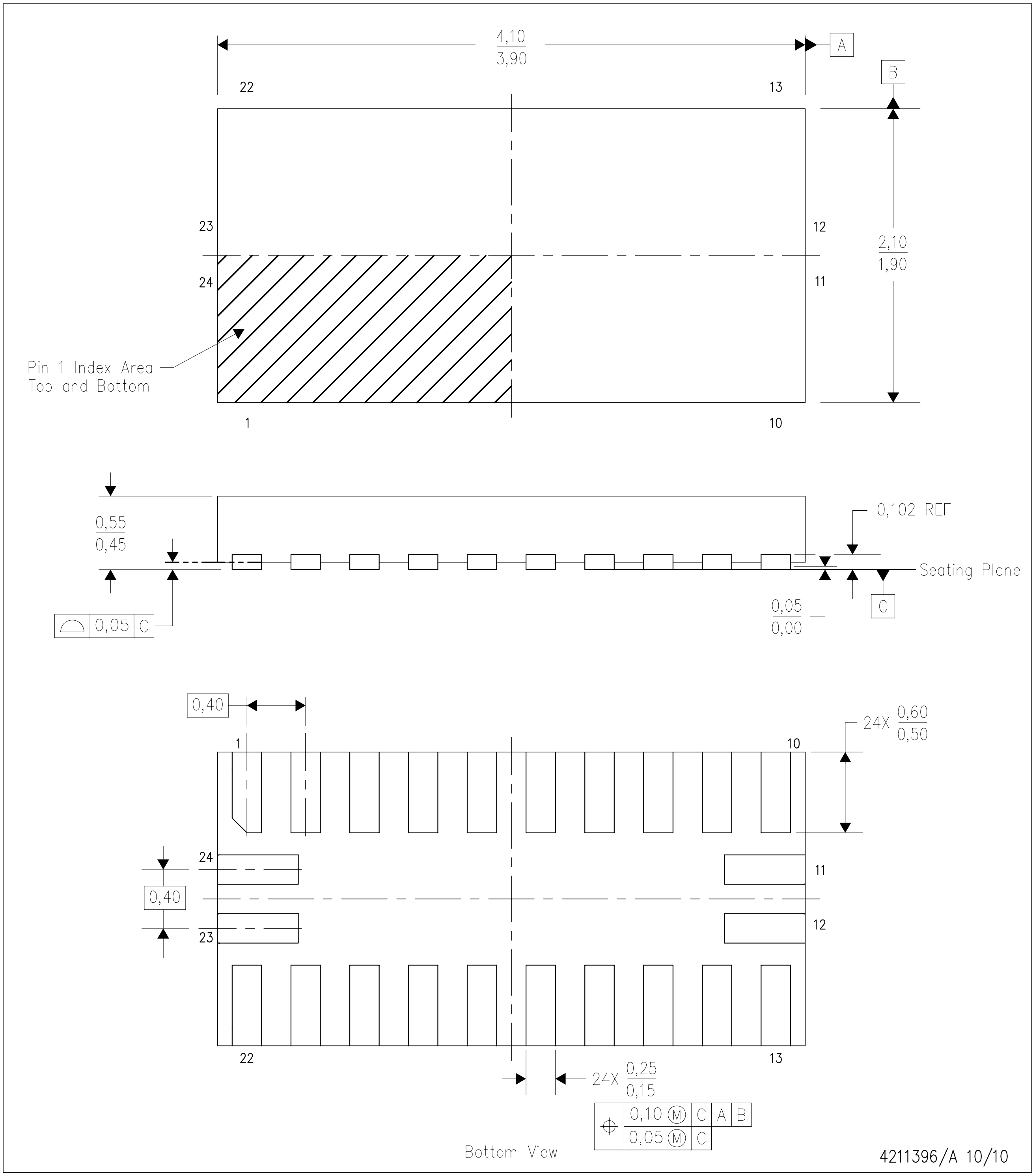
PW (R–PDSO–G24) PLASTIC SMALL OUTLINE



4211284–4/F 12/12

NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

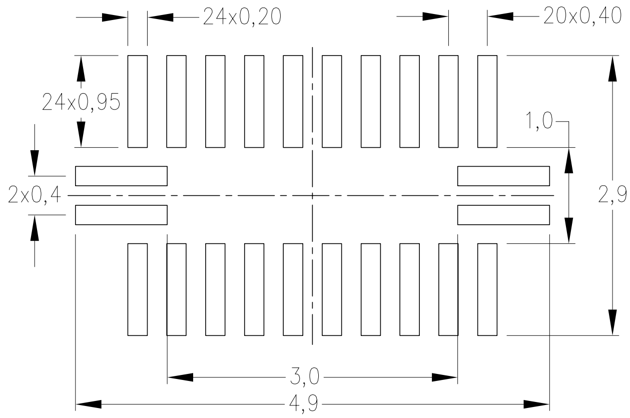
RKT (R–PUQFN–N24) PLASTIC QUAD FLATPACK NO–LEAD



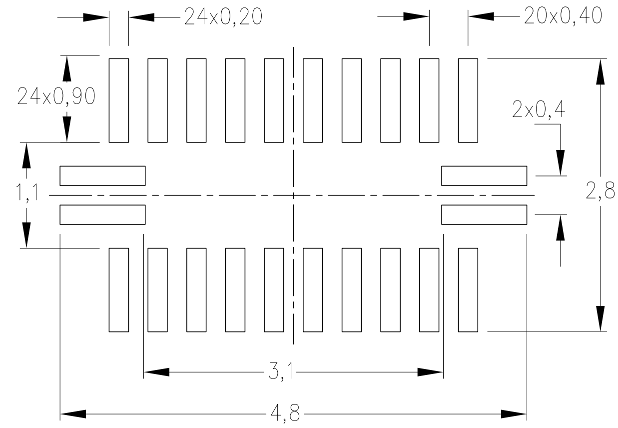
NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No–Lead) package configuration.

RKT (R–PUQFN–N24) PLASTIC QUAD FLATPACK NO–LEAD

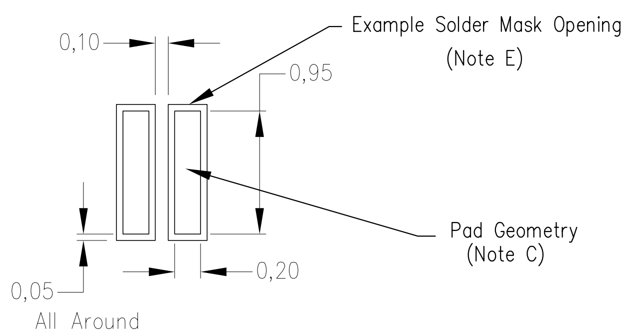
Example Board Layout



Example Stencil Design
0.125 Thick Stencil
(Note D)



Non Solder Mask Defined Pad



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NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC–7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- E. Customers should contact their board fabrication site for recommended solder mask tolerances between and around signal pads

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